L Number	Hits	Search Text	DB	Time stamp
1	233	257/666.ccls. and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/20 11:39
2	198	(257/666.ccls. and laser) and (@ad<20020128)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/20 12:04
3	280	257/666.ccls. and (laser or (light adjemitting))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 12:02
5	12	((257/666.ccls. and (laser or (light adjemitting))) and (@ad<20020128)) and (light adj receiving)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 11:40
4	238	(257/666.ccls. and (laser or (light adjemitting))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:08
6	362	257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20
7	359	(257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)) not ((257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20
8	221		USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/20 11:52
9	59646		IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/20 12:03
10	59647	<pre>(light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 12:04
11	53211	((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 12:04
12	1813	<pre>(((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:07
13	262		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TOB	2004/07/20 12:06

14	75	257/80.ccls. and (encapsulant or	USPAT;	2004/07/20
1 1 1	/ /	encapsulate or mold or molding or epoxy)	US-PGPUB;	12:06
		and (@ad<20020128)	EPO; JPO;	12.00
		and (ead\20020120)	DERWENT;	
			IBM TDB	
15	103	257/79.ccls. and (encapsulant or	USPAT;	2004/07/20
13	103			12:06
		encapsulate or mold or molding or epoxy)	US-PGPUB;	12:06
		and (@ad<20020128)	EPO; JPO;	
			DERWENT;	
1	_		IBM_TDB	0004/07/00
16	0	((((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:07
		(light adj (emitting or emitter)))) and	EPO; JPO;	
İ		(@ad<20020128)) and (encapsulant or	DERWENT;	
	i	encapsulate or mold or molding or epoxy)	IBM_TDB	
		and (lead or leads)) and 385/\$.ccls		
17	2041	((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:07
		(light adj (emitting or emitter)))) and	EPO; JPO;	
		385/\$.ccls.	DERWENT;	
			IBM_TDB	
18	249	((((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:08
1		(light adj (emitting or emitter)))) and	EPO; JPO;	
		(@ad<20020128)) and (encapsulant or	DERWENT;	
		encapsulate or mold or molding or epoxy)	IBM_TDB	
		and (lead or leads)) and 385/\$.ccls.		
19	244	(((((light adj (receiving or sensor or	USPAT;	2004/07/20
1		receivor)) and (laser or photodiode or	US-PGPUB;	12:08
]	(light adj (emitting or emitter)))) and	EPO; JPO;	
		(@ad<20020128)) and (encapsulant or	DERWENT;	1
		encapsulate or mold or molding or epoxy)	IBM_TDB	
		and (lead or leads)) and 385/\$.ccls.) not	_	
		(257/98.ccls. and (encapsulant or		
		encapsulate or mold or molding or epoxy)	i	
		and (@ad<20020128))		
20	244	((((((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:08
		(light adj (emitting or emitter)))) and	EPO; JPO;	
		(@ad<20020128)) and (encapsulant or	DERWENT;	
		encapsulate or mold or molding or epoxy)	IBM_TDB	
		and (lead or leads)) and 385/\$.ccls.) not		
		(257/98.ccls. and (encapsulant or		
		encapsulate or mold or molding or epoxy)		
		and (@ad<20020128))) and (@ad<20020128)	L	